ON Semiconductor®

Product Bulletin

Document # : PB22055X
Issue Date: 9 November 2017

Title of Change:	MT9V115 Datasheet Update.
Effective date:	9 November 2017
Contact information:	Contact your local ON Semiconductor Sales Office or <Sonya.Yip@onsemi.com>
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☒ Other Documentation

Change Sub-Category(s):

☐ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☒ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: ______________________

Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: None

Description and Purpose:

MT9V115 Datasheet was updated to correct documentation errors. The changes will not impact form, fit, or function of products.

MT9V115 Datasheet Changes

1. Changed incorrect figure reference from "Figure 12 to Figure 14" to "Figure 12 to Figure 13"

Old Reference:

Figure 12 through Figure 14 show the different skipping modes supported in MT9V115.

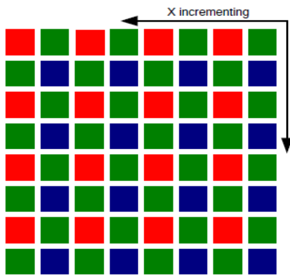


Figure 12. Pixel Readout (no skipping)

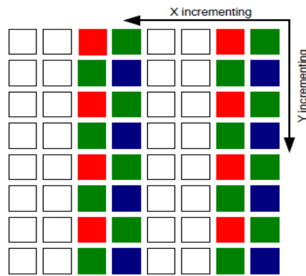


Figure 13. Pixel Readout (x odd inc = 3, y odd inc = 1)

New Reference:

Figures 12 and 13 show the different skipping modes supported in MT9V115.

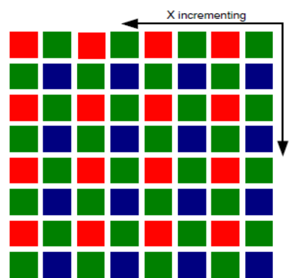


Figure 12. Pixel Readout (no skipping)

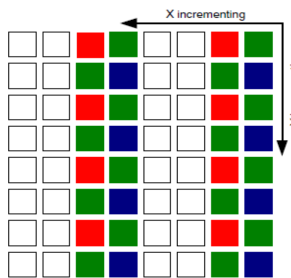


Figure 13. Pixel Readout

2. Changed preliminary package drawing to official ON Semi Case outline

Old Preliminary Package Drawing:

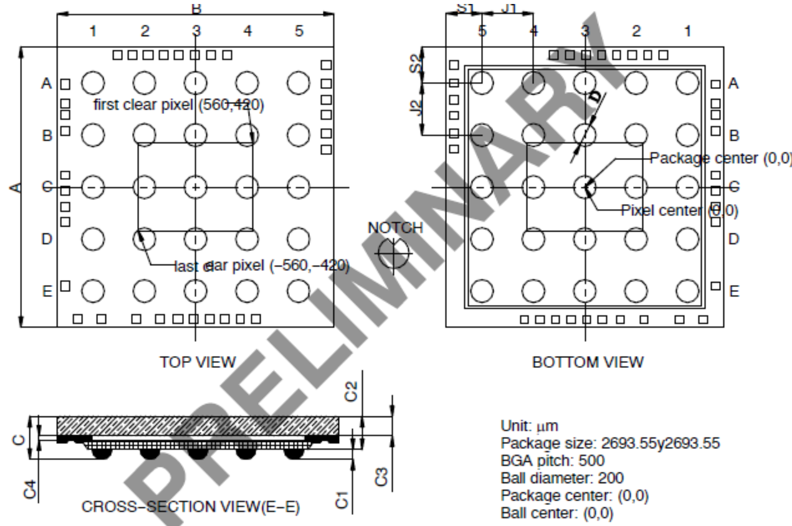
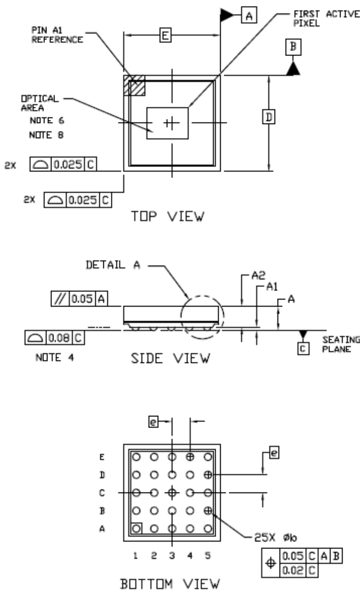


Figure 36. Package Mechanical Drawing (CASE 570BK)

New Final Release Package Drawing:

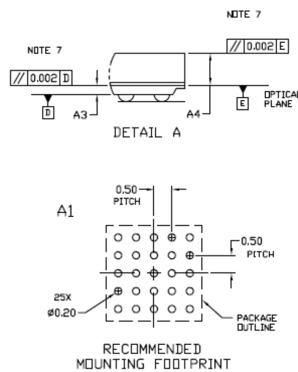
PACKAGE DIMENSIONS

ODCSP25 2.694x2.694
CASE 570BK
ISSUE B



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE SOLDER BALLS.
6. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO D AND E WILL BE 0.1°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATASHEET FOR TOTAL ARRAY AND FIRST ACTIVE PIXEL DEFINITIONS.
7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X=−130 MICRONS, Y=0.00 MICRONS ±25 MICRONS.



DIM	MILLIMETERS	
	MIN.	MAX.
A	---	0.73
A1	0.07	0.13
A2	0.57 REF	
A3	0.109	0.149
A4	0.431	0.451
b	0.175	0.225
D	2.694 BSC	
E	2.694 BSC	
e	0.50 BSC	

List of Affected Parts:

MT9V115D00STCK22EC1-200
MT9V115EBKSTC-CR
MT9V115W00STCK22EC1-750

ON Semiconductor®

Appendix A: Changed Products

D

Product	Customer Part Number
MT9V115EBKSTC-CR	